



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP20583	REV: A	SVN REV: Not In VersionControl
	TID #: PMP20583		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/28/2016 12:26:39 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP20583	REV: A	SUN REV: Not In VersionControl
	TID #: PMP20583		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/28/2016 12:26:41 PM		TEXAS INSTRUMENTS

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